

IMPROVEMENTS IN GROUNDING AND THERMAL DISSIPATION FOR INTE- GRATED CIRCUIT PACKAGES

Abstract

In a microelectronic chip package for which grounding and thermal dissipation is desired, a cover is provided having an opening which is aligned with a contact on the substrate connected to ground potential. The cover is connected to the electronic device and the ground contact. This invention provides for a method and electronic package to overcome the difficulties encountered when attempting to simultaneously attach a cover to two different surfaces with two different adhesives.